



Patent

In re application of:
Rich Fogal and Michael B. Ball

Serial No.: 09/422,887

Filed: October 21, 1999

For: ANGULARLY OFFSET STACKED
DIE MULTICHIP DEVICE AND METHOD
OF MANUFACTURE

§ Group Art Unit: 2822
§ Examiner: J. Davis
§ Atty. Docket: 95-0134.05

Certificate of Mailing (37 C.F.R. § 1.8)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date below:

5-15-01

Date

Rich Fogal
Signature

PETITION FOR EXTENSION OF TIME UNDER 37 C.F.R. § 1.136(a)

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Applicant hereby petitions to extend the period for response to the Office Action mailed 11/16/00 for three (3) months, from 2/16/01 to 5/16/01.

Accordingly, the requisite fee is \$ 890. The Commissioner is requested to charge this fee, and any additional fee which may be required to Micron Technology, Inc. Deposit Account 13-3092, Order No. 95-0134.05. A duplicate copy of this petition is enclosed.

Respectfully submitted,

Charles Brantley

Charles Brantley
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Date: 5/15/01

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